

ABSTRACT

Disclosed is a method for removing material from a high speed, moving substrate. This method includes the steps of: supplying a moving substrate having at least one first
5 portion and at least one second portion, providing a cutter and using the cutter to substantially sever the first portion from the second portion, nipping the first portion between a movable mechanical finger and a movable complementary surface, and moving the second portion away from the first portion while the first portion is maintained
10 in contact between the movable mechanical finger and the movable complementary surface.